



Final Product/Process Change Notification

Document #:FPCN25918X

Issue Date: 28 Jun 2024

Title of Change:	Transfer of Assembly operation of DFN10 package from onsemi Seremban, Malaysia to UTAC THAI LIMITED, Thailand.													
Proposed First Ship date:	05 Oct 2024 or earlier if approved by customer													
Contact Information:	Contact your local onsemi Sales Office or Milos.Dvorak@onsemi.com													
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.													
Additional Reliability Data:	Contact your local onsemi Sales Office or Vladislav.Hrachovec@onsemi.com													
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com													
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code and custom source.													
Change Category:	Assembly Change													
Change Sub-Category(s):	Manufacturing Site Transfer													
Sites Affected:														
onsemi Sites	External Foundry/Subcon Sites													
None	UTAC, Thailand													
Description and Purpose:														
This Final Notification announces to customers of onsemi's plans to Transfer Assembly operation of the DFN10 package products from onsemi Seremban, Malaysia to UTAC THAI LIMITED, Thailand.														
	<table><thead><tr><th></th><th>From</th><th>To</th></tr></thead><tbody><tr><td>Assembly Site</td><td>onsemi, Seremban, Malaysia</td><td>UTAC THAI LIMITED, Thailand.</td></tr><tr><td>Die Attach</td><td>CRM1084P</td><td>ABLETHERM 8600</td></tr><tr><td>Mold Compound</td><td>EMEG760</td><td>G770HCD</td></tr></tbody></table>		From	To	Assembly Site	onsemi, Seremban, Malaysia	UTAC THAI LIMITED, Thailand.	Die Attach	CRM1084P	ABLETHERM 8600	Mold Compound	EMEG760	G770HCD	
	From	To												
Assembly Site	onsemi, Seremban, Malaysia	UTAC THAI LIMITED, Thailand.												
Die Attach	CRM1084P	ABLETHERM 8600												
Mold Compound	EMEG760	G770HCD												
There is no product marking change as a result of this change.														



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Reliability Data Summary:

QV DEVICE NAME: NCV51510MWTAG

RMS: S30085

PACKAGE: DFN10

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/80
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/80
Preconditioning	J-STD-020 JESD-A113	MSL1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only		0/720
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/240
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/240
Autoclave	JESD22-A102	121°C, 100% RH, 29.7psig, unbiased	96 hrs	0/240
Electrical Distribution	onsemi DataSheet	Cpk ≥ 1.67; Test @ Room & Hot & Cold	Electrical	0/90

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [**PCN Customized Portal**](#).

Part Number	Qualification Vehicle
NCP51403MNTXG	NCV51510MWTAG
NCP51402MNTXG	NCV51510MWTAG
NCP51401MNTXG	NCV51510MWTAG
NCP51400MNTXG	NCV51510MWTAG
NCP51200MNTXG	NCV51510MWTAG
NCP51200AMNTXG	NCV51510MWTAG